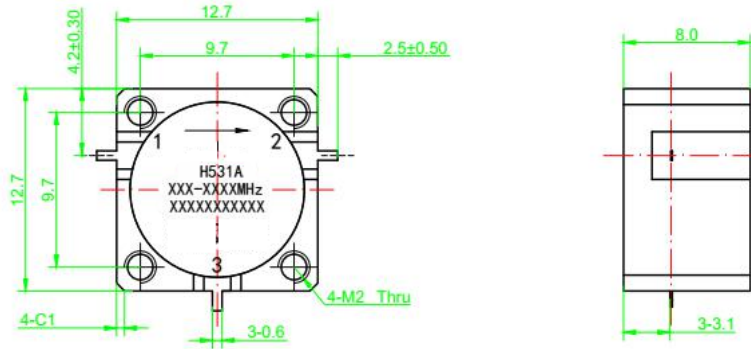


## 1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40~ 85°C
- Compact Package Design for PCB Applications

## 2.Dimensions Unit:mm



## 3.Specifications

Part No.	Frequency (GHz)		Center Frequency (GHz)	Bandwidth (GHz)	Isolation (dB) MIN	INS LOSS (dB) MAX	VSWR (dB) MAX	Power (W)	IMD (@2X43dBm) (-dBc) MAX
	F1	F2							
H531A[1805-1880]MHz	1.805	1.880	1.8425	0.075	22	0.35	1.17	100	
H531A[1805-2025]MHz	1.805	2.025	1.915	0.220	18	0.35	1.28	75	
H531A[2000-2100]MHz	2.000	2.100	2.0500	0.100	20	0.35	1.22	75	
H531A[2110-2170]MHz	2.110	2.170	2.140	0.060	22	0.3	1.17	100	
H531A[2100-2200]MHz	2.100	2.200	2.150	0.100	20	0.35	1.22	75	
H531A[2300-2400]MHz	2.300	2.400	2.350	0.100	23	0.3	1.15	75	
H531A[2400-2550]MHz	2.400	2.550	2.475	0.150	23	0.3	1.15	75	
H531A[2500-2700]MHz	2.500	2.700	2.600	0.200	22	0.3	1.17	100	-75